

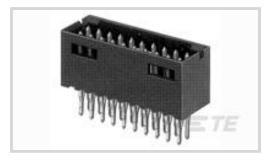
AMPMODU | AMPMODU Headers

TE Internal #: 5-102699-7 PCB Mount Header, Vertical, Wire-to-Board / Board-to-Board, 16 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board, Wire-to-Board

Number of Positions: 16

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board, Wire-to-Board

Fully Shrouded

| Connector & Contact | Terminates To |
|---------------------|---------------|
|---------------------|---------------|

Printed Circuit Board

Configuration Features

| Connector Contact Load Condition | Fully Loaded |
|---|-------------------------------|
| PCB Mount Orientation | Vertical |
| Number of Positions | 16 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |
| Electrical Characteristics | |
| Insulation Resistance | 5000 MΩ |
| Dielectric Withstanding Voltage (Max) | 750 Vrms |
| Body Features | |
| Primary Product Color | Black |
| Contact Features | |
| Mating Square Post Dimension | .64 mm[.025 in] |
| PCB Contact Termination Area Plating Material Thickness | 2.54 – 5.08 μm[100 – 200 μin] |

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| Contact Shape & Form | Square |
|--|----------------------------|
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .762 μm[30 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |
| Termination Features | |
| Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Termination Post & Tail Length | 6.35 mm[.25 in] |
| Termination Method to Printed Circuit Board | Through Hole - Press-Fit |
| Mechanical Attachment | |
| Mating Retention | With |
| PCB Mount Retention Type | Action/Compliant Tail |
| Mating Retention Type | Detent Window |
| Mating Alignment | With |
| Mating Alignment Type | Polarization |
| PCB Mount Retention | With |
| PCB Mount Alignment | With |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Material | Thermoplastic |
| Dimensions | |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| Usage Conditions | |
| Housing Temperature Rating | High |
| Operating Temperature Range | -55 – 105 °C[-67 – 221 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |

C For support call+1 800 522 6752

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| Agency/Standard | CSA |
|---|------------------------|
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 130 |
| Packaging Type | Tray |
| Product Compliance | |
| For compliance documentation, visit the product page on TE.com> | |
| EU RoHS Directive 2011/65/EU | Compliant |
| | Compliant Compliant |
| EU RoHS Directive 2011/65/EU | |
| EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC | Compliant |

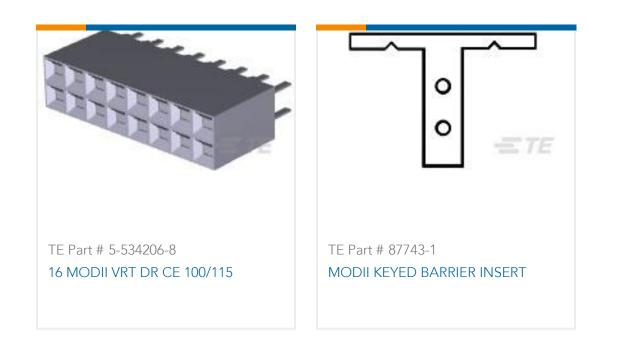
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts

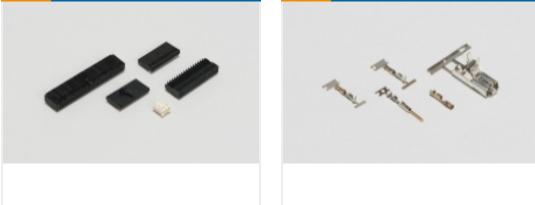
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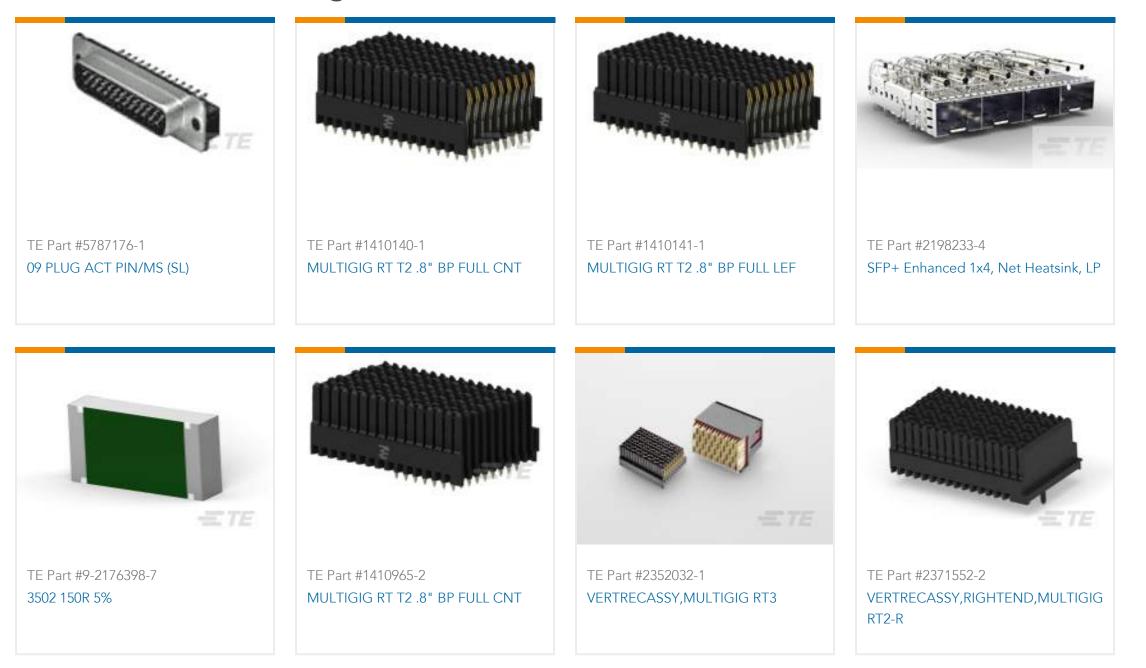
Also in the Series AMPMODU Headers





| Wire-to-Board Connector Assemblies | Wire-to-Board Connector Contacts(65) |
|------------------------------------|--------------------------------------|
| & Housings(5) | |

Customers Also Bought



PCB Mount Header, Vertical, Wire-to-Board / Board-to-Board, 16 Position, 2.54 mm [. 1 in] Centerline, Fully Shrouded, Gold, AMPMODU Headers



-TE TE Part #2327906-4 KEYED GUIDE PIN, MACHINED, MULTIGIG BP

Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-102699-7_M.2d_dxf.zip

English

Customer View Model ENG_CVM_CVM_5-102699-7_M.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-102699-7_M.3d_stp.zip

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English

Product Specifications Application Specification

English

Product Environmental Compliance **TE Material Declaration**

English